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PATENT REEL: 013559 FRAME: 0276

ASSIGNMENT

WHEREAS, I, Eric Peng Huat Yap, the undersigned inventor (ASSIGNOR), have invented SAM-PLE PREPARATION INTEGRATED CHIP, having U.S. Serial Number 10/279,627 filed October 24, 2002, for which I have filed application for letters patent of the United States. I am a joint owner of this invention and improvements.

WHEREAS, DEFENSE SCIENCE AND TECHNOLOGY AGENCY, (ASSIGNEE) is a statutory board organized and existing under the laws of Singapore having an address at 71 Science Park Drive, #02-05, Singapore 118253. ASSIGNEE desires to acquire the entire right, title and interest in and to the inventions, applications and letters patent to be granted and issued for the inventions and applications.

NOW, THEREFORE, for and in consideration of the sum of Ten Dollars (\$10.00) by the ASSIGNEE to each of us paid, and other valuable consideration, the receipt and legal sufficiency of all of which we acknowledge, we, the ASSIGNORS, have sold and do hereby sell, assign, transfer and set over unto the ASSIGNEE, its successors and assigns, the entire right, title and interest:

in and to the inventions and all improvements thereon,

in and to the application for letters patent thereon,

in and to applications pertaining to or based upon the inventions and applications, including divisional and continuing applications, continuations-in-part, reissues and reexaminations,

in and to any and all letters patent which may be granted and issued on the inventions and applications, or any of them, not only for, to and in the United States of America, its territories and possessions, but for, to and in all foreign countries, together with and including all priority rights based upon any and all applications in the United States of America covered by this Assignment, and

in and to any right to sue for past infringement of the inventions, improvements, applications and letters patent.

And for the above-named considerations, we agree that we will, at the request of the ASSIGNEE, execute any and all applications for letters patent for the inventions and any and all other papers and documents and do all other and further lawful acts that the ASSIGNEE may deem necessary or desirable to obtain letters patent on the inventions, to secure the grant of such letters patent and to perfect and vest in the ASSIGNEE the entire right, title and interest in the inventions, applications and letters patent.

And for the above-named considerations, we authorize and empower the ASSIGNEE, its successors and assigns, to apply for and obtain, in its or their own names, letters patent for the inventions before competent International Authorities including the World Intellectual Property Office and in any and all countries foreign to the United States in which applications for letters patent can be so made or letters patent so obtained.

Dated: 15 No√____, 2002

Name: Eric Peng Huat Yap

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RECORDED: 12/10/2002

PATENT REEL: 013559 FRAME: 0277